2SJ0672

Silicon P-channel MOSFET

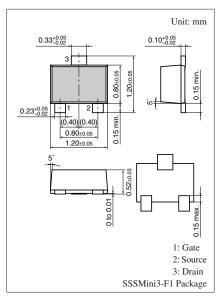
For switching circuits

■ Features

- Ultra small package switching MOSFETs
- SSS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source voltage	V _{DS}	-30	V	
Gate-source voltage (Drain open)	V_{GSO}	±7	V	
Drain current	I_{D}	-100	mA	
Peak drain current	I_{DP}	-200	mA	
Power dissipation	P_{D}	100	mW	
Channel temperature	T _{ch}	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



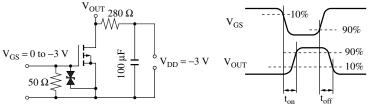
Marking Symbol: 5M

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	V _{DSS}	$I_D = -10 \mu\text{A}, V_{GS} = 0$	-30			V
Drain-source cutoff current	I_{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0$			- 0.1	μΑ
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 7 \text{ V}, V_{DS} = 0$			±10	μΑ
Gate threshold voltage	V _{th}	$V_{DS} = -3.0 \text{ V}, I_{D} = -1.0 \mu\text{A}$	- 0.5	-1.0	-1.5	V
Forward transfer admittance	Y _{fs}	$V_{DS} = 3 \text{ V}, I_{D} = 10 \text{ mA}, f = 1 \text{ kHz}$	20	35		mS
Drain-source ON resistance	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_{D} = -10 \text{ mA}$		20	45	Ω
		$V_{GS} = -4.0 \text{ V}, I_{D} = -10 \text{ mA}$		15	30	
Short-circuit forward transfer	C _{iss}	$V_{DS} = -3 \text{ V}, V_{GS} = 0, \text{ f} = 1 \text{ MHz}$		10		pF
capacitance (Common source)				-		
Short-circuit output capacitance (Common source)	C _{oss}			7		
Reverse transfer capacitance (Common source)	C _{rss}			3		
Turn-on time *	t _{on}	$V_{DD} = -3 \text{ V}, V_{GS} = 0 \text{ V} \sim -3 \text{ V}$		850		ns
		$I_D = -10 \text{ mA}$				
Turn-off time *	t _{off}	$V_{DD} = -3 \text{ V}, V_{GS} = -3 \text{ V} \sim 0 \text{ V}$		850		ns
		$I_D = -10 \text{ mA}$				

 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7030 \ measuring \ methods \ for \ transistors.$

2. *: t_{on} , t_{off} test circuit



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